

S	PECIFICATIONS			
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MASS PRODUCTION CODE	: PH240320T075-ZEA04			
SAMPLE VERSION	· 01			
SPECIFICATIONS EDITION	. 002			
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	stomer Approved	Date: JS RD APPROVED		
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 Preliminary specification for Specification for sample appreciation 	- .			
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History of Version

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					otal: 29 Pages

Total: 29 Pages



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1. SPECIFICATIONS

1.1 Features

<u>ltem</u>	Standard Value		
Display Type	240 * 3 (RGB) * 320 Dots		
LCD Type	Full Viewing Angle , Normally Black , Transmissive type		
Screen size(inch)	2.8 inch		
Color configuration	RGB-Strip		
Interface	16-bits 8080 Interface		
Other (controller/driver IC)	ST7789T3-G4-1		
Other(controller/driver IC)	(Or Compatible IC)		
	THIS PRODUCT CONFORMS THE ROHS OF PTC		
ROHS	Detail information please refer website:		
	http://www.powertip.com.tw/news_detail.php?Key=1&cID=1		

Note : For detailed information please refer to IC data sheet :

Primacy(TFT LCD): Sitrnox ST7789T3-G4-1 (Or Compatible IC)

1.2 Mechanical Specifications

<u>ltem</u>	Standard Value	<u>Unit</u>
Outline Dimension	50.0(W) *69.2 (L) *2.45(H)	mm

LCD Panel

<u>Item</u>	Standard Value	<u>Unit</u>
Active Area	43.2(W) *57.6 (L)	mm
Pixel Size	0.18(W) *0.18 (H)	mm

Note : For detailed information please refer to LCM drawing



1.3 Absolute Maximum Ratings

<u>ltem</u>	<u>Symbol</u>	<u>Condition</u>	<u>Min.</u>	Max.	<u>Unit</u>
System Power Supply Voltage	VCC	GND=0	-0.3	4.6	V
Operating Temperature	Top (Ts)	Note 1	-20	70	°C
Storage Temperature	Ts⊤(Ta)	Note 2	-30	80	°C
Storage Humidity	HD	Ta ≦ 60 °C	10	90	%RH

The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

Note 1 : Ts is the temperature of panel's surface.

Note 2: Ta is the ambient temperature of samples.

1.4 DC Electrical Characteristics

GND = 0V, Ta = 25°C

<u>ltem</u>	<u>Symbol</u>	Condition	<u>Min.</u>	<u>Typ.</u>	<u>Max.</u>	<u>Unit</u>
Power Supply Voltage	VCC		2.4	2.8	3.3	V
Input H/L Level Voltage	VIH		0.7VCC	-	VCC	V
	VIL	-	GND	-	0.3VCC	V
Supply Current	Idd	VCC =2.8 V	-	10	15	mA



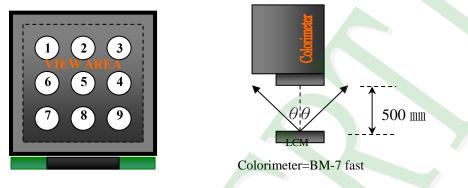
1.5 Optical Characteristics

VCC=2.8V, Ta=25°C								
<u>ltem</u>	<u>Syr</u>	<u>nbol</u>	<u>Condition</u>	<u>Min.</u>	<u>Тур.</u>	Max.	<u>unit</u>	
Response time	Tr	+Tf	Ta = 25°C θX, θY = 0°	-	40	60	ms	Note 2
	Тор	θY+		-	80	1		
Viewing angle	Bottom	θY-	CR ≥ 10	-	80	1	Deg.	Note 4
	Left	θХ-			80	1	Deg.	NOLE 4
	Right	θX+		-	80	-		
Contrast ratio)	CR		650	800	-		Note 3
	White	Х		0.22	0.27	0.32		
	Red	Y		0.25	0.30	0.35		
		Х	$T_{2} = 05^{\circ}O$	0.59	0.64	0.69		
Color of CIE	Reu	Y	Ta = 25°C θX , θY = 0°	0.28	0.33	0.38		Note1
Coordinate	Green	Х		0.25	0.30	0.35	-	NOLET
	Green	Y		0.58	0.63	0.68		
	Blue	X		0.10	0.15	0.20		
	Dide	Y		0.00	0.05	0.10		
Average Brightness (With LCD)*1		F	IF= 80 mA	300	350	-	cd/m ²	Note1
Uniformity (With LCD)*2		Ъ	IF=80 mA	70	-	-	%	Note1



Note 1:

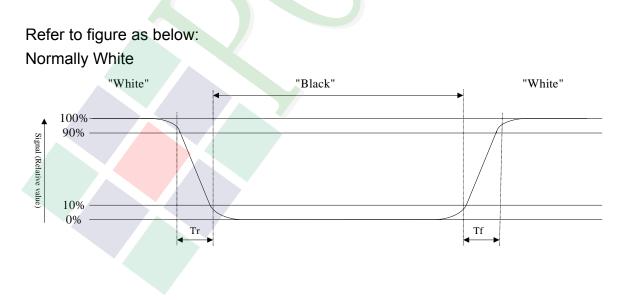
- *1 : △B=B(min) / B(max) * 100%
- *2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25°C ±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: 500 \pm 50 mm \rightarrow (θ = 0°)
 - c : Equipment: TOPCON BM-7 fast , (field 1°) , after 10 minutes operation.
 - d: The uncertainty of the C.I.E coordinate measurement ±0.01 , Average Brightness ± 4%



To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

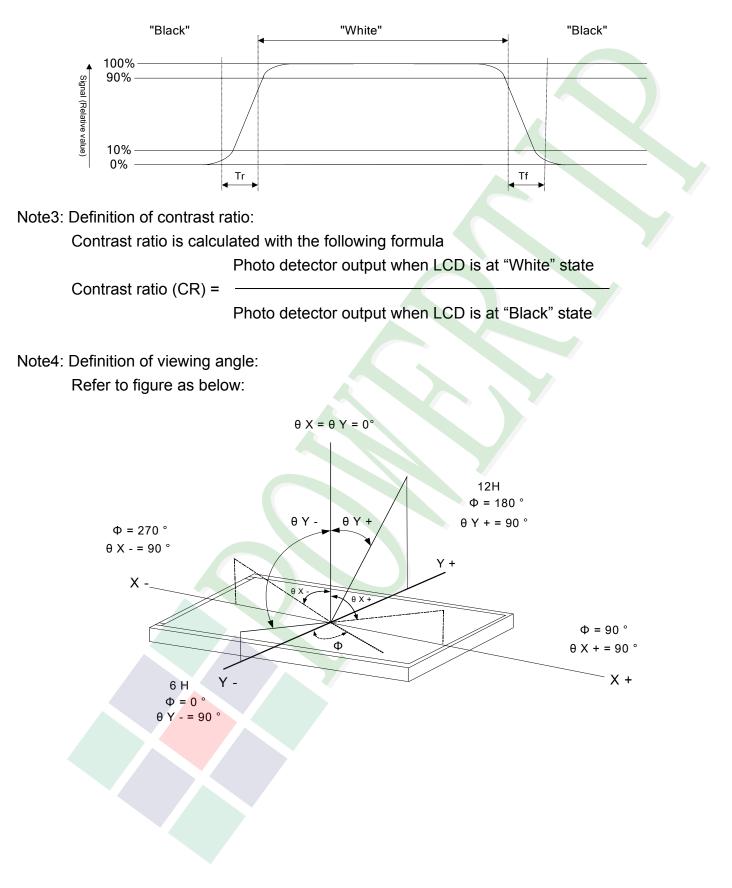
Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.





Normally Black





1.6 Backlight Unit Characteristics

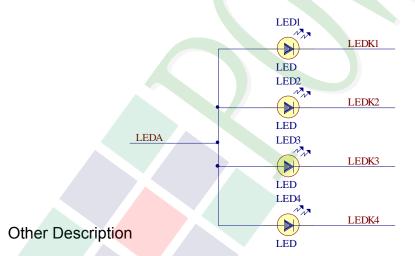
Maximum Ratings

<u>ltem</u>	<u>Symbol</u>	Conditions	<u>Min.</u>	Max.	<u>Unit</u>
LED Forward Current	IF		-	30/Per LED	mA
LED Reverse Voltage	VR	Ta =25℃	-	5	V
Power consumption	Pd			288	mW

Electrical / Optical Characteristics

<u>ltem</u>	<u>Symbol</u>	<u>Conditions</u>	<u>Min.</u>	<u>Typ.</u>	<u>Max.</u>	<u>Unit</u>
Forward Voltage	VF		2.8	3.2	3.6	
Average Brightness (Without LCD)	IV	lf= 80mA	8500	10000	X -	cd/m ²
CIE Color Coordinate	Х		0.26	0.28	0.33	
(Without LCD)	Y		0.26	0.28	0.33	-
Color			White			

B/L Internal Circuit Diagram:



ltem	<u>Conditions</u>	Description
Life Time	Ta =25℃ IF= 80mA	50,000 hrs



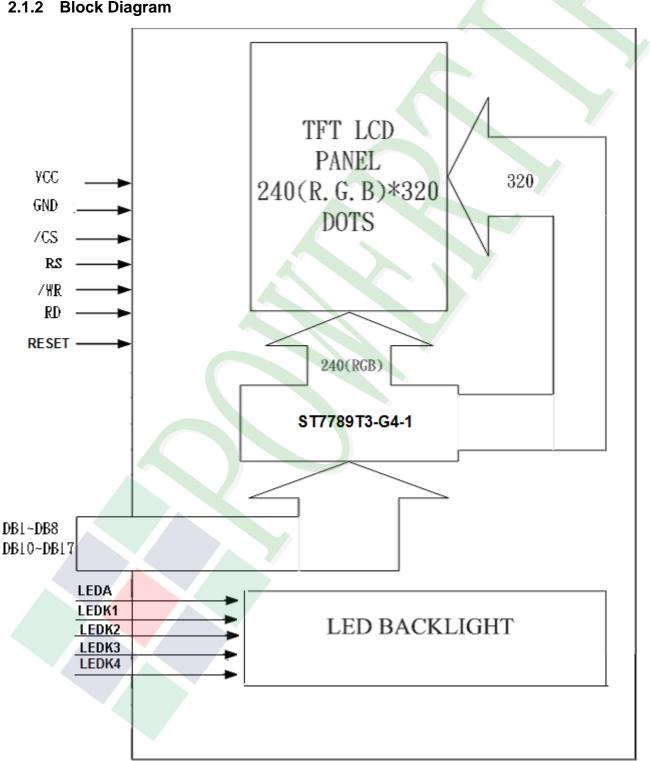
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





2.2 Interface Pin Description

Pin No.	<u>Symbol</u>	Function
1	DB1	Bi-directional data bus
2	DB2	Bi-directional data bus
3	DB3	Bi-directional data bus
4	DB4	Bi-directional data bus
5	GND	Signal ground.(0V)
6	VCC	Power supply for the internal logic circuit
7	/CS	Chip select signal , Active at "L"
8	RS	When RS = 0: Command. When RS = 1: Display data
9	/WR	Write signal input , active at Low.
10	RD	Read data at the rising edge
11	NC	No connect
12	XR/X+	No connect
13	YU/Y+	No connect
14	XL/X-	No connect
15	YD/Y-	No connect
16	LEDA	Power supply for LED Backlight Anode input
17	LEDK1	Power supply for LED Backlight Cathode input
18	LEDK2	Power supply for LED Backlight Cathode input
19	LEDK3	Power supply for LED Backlight Cathode input
20	LEDK4	Power supply for LED Backlight Cathode input
21	NC	No connect
22	DB5	Bi-directional data bus
23	DB10	Bi-directional data bus
24	DB11	Bi-directional data bus
25	DB12	Bi-directional data bus

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<u>Pin No.</u>	<u>Symbol</u>	Function
26	DB13	Bi-directional data bus
27	DB14	Bi-directional data bus
28	DB15	Bi-directional data bus
29	DB16	Bi-directional data bus
30	DB17	Bi-directional data bus
31	RESET	Reset input pin for TFT LCD.
	REGET	When RESET is "L", initialization is executed
32	VCC	Power supply for the internal logic circuit.
33	VCC	Power supply for the internal logic circuit.
34	GND	Signal ground.(0V)
35	DB6	Bi-directional data bus
36	DB7	Bi-directional data bus
37	DB8	Bi-directional data bus



2.2.1 Refer Initial code:

void Initial_Main(void)

// For ST7789VI

{

WriteCOM_Main(0x00,0x11);//exit sleep Delay(120); WriteCOM_Main(0x00,0x36); //Memory access Control WriteDAT_Main(0x00,0x00);

WriteCOM_Main(0x00,0x3A); //Interface pixel format
WriteDAT_Main(0x00,0x05);

//-----ST7789VI Frame rate setting-----//

WriteCOM_Main(0x00,0xB2); WriteDAT_Main(0x00,0x0c); WriteDAT_Main(0x00,0x0c); WriteDAT_Main(0x00,0x00); WriteDAT_Main(0x00,0x33); WriteDAT_Main(0x00,0x33);

WriteCOM_Main(0x00,0xB7); WriteDAT_Main(0x00,0x35); //-----ST7789VI Power setting------//

WriteCOM_Main(0x00,0xbb); //VCOMS Setting
WriteDAT_Main(0x00,0x3D);

WriteCOM_Main(0x00,0xc0); WriteDAT_Main(0x00,0x2c);

WriteCOM_Main(0x00,0xc2); WriteDAT_Main(0x00,0x01);

WriteCOM_Main(0x00,0xc3); WriteDAT_Main(0x00,0x0B);



WriteCOM_Main(0x00,0xc4); WriteDAT_Main(0x00,0x20);

WriteCOM_Main(0x00,0xc6); WriteDAT_Main(0x00,0x0f);

WriteCOM_Main(0x00,0xd0); WriteDAT_Main(0x00,0xa4); WriteDAT_Main(0x00,0xa1);

WriteCOM_Main(0x00,0x21);

//-----set gamma------

WriteCOM_Main(0x00,0xe0); //set gamma
WriteDAT_Main(0x00,0x70);
WriteDAT_Main(0x00,0x04);
WriteDAT_Main(0x00,0x07);
WriteDAT_Main(0x00,0x06);
WriteDAT_Main(0x00,0x04);
WriteDAT_Main(0x00,0x42);
WriteDAT_Main(0x00,0x38);
WriteDAT_Main(0x00,0x37);
WriteDAT_Main(0x00,0x13);
WriteDAT_Main(0x00,0x25);
WriteDAT_Main(0x00,0x2C);

WriteCOM_Main(0x00,0xe1); //set gamma WriteDAT_Main(0x00,0x70); WriteDAT_Main(0x00,0x00); WriteDAT_Main(0x00,0x02); WriteDAT_Main(0x00,0x08); WriteDAT_Main(0x00,0x07); WriteDAT_Main(0x00,0x22); WriteDAT_Main(0x00,0x1F);



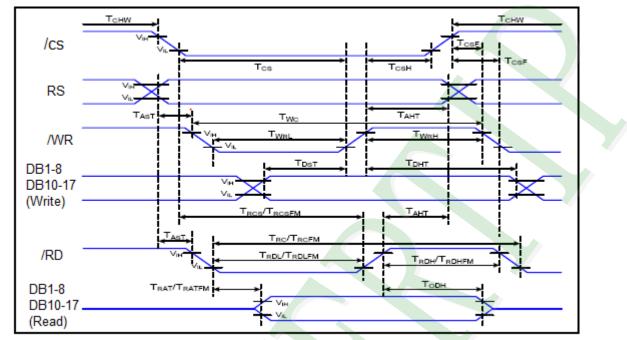
WriteDAT_Main(0x00,0x23); WriteDAT_Main(0x00,0x39); WriteDAT_Main(0x00,0x28); WriteDAT_Main(0x00,0x14); WriteDAT_Main(0x00,0x15); WriteDAT_Main(0x00,0x26); WriteDAT_Main(0x00,0x2D);

}

WriteCOM_Main(0x00,0x29);//Display on

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2.3 Timing Characteristics



8080 Series MCU Parallel Interface Characteristics:18/16/9/8-Bit Bus

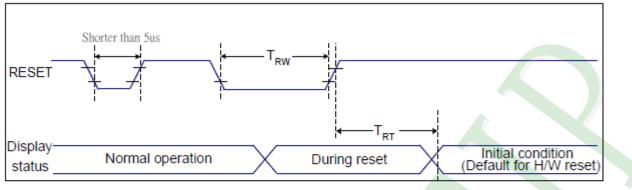
Parallel Interface Timing Characteristics (8080-Series MCU Interface)



			VC	C= 2.8V, T	a=25℃
<u>Signal</u>	<u>Symbol</u>	Parameter	<u>Min</u>	<u>Max</u>	<u>Unit</u>
RS	TAST	Address Setup time	0	-	ns
RO	TAHT	Address Hold time(Write/Read)	10	-	ns
	TCHW	Chip select "H" pulse width	0	-	20
	TCS	Chip select Setup time (Write)	15	-	ns
/CS	TRCS	Chip Select setup time (Read ID)	45		ns
105	TRCSFM	Chip select Setup time (Read FM)	355	-	ns
	TCSF	Chip select wait time(Write/Read)	10		ns
	TCSH	Chip select hold time	10	-	ns
	TWC	Write Cycle	66	-	ns
/WR	TWRH	Control pulse "H" duration	15	-	ns
	TWRL	Control pulse "L" duration	15	-	ns
	TRCFM	Read Cycle(FM)	450	_	ns
RD(FM)	TRDHFM	Read Control "H" duration (FM)	90	-	ns
	TRDLFM	Read Control "L" duration (FM)	355	-	ns
	TRC	Read Cycle(ID)	160		ns
RD(ID)	TRDH	Control pulse "H" duration(ID)	90		ns
	TRDL	Control pulse "L" duration(ID)	45		ns
	TDST	Data setup time	10		ns
DB1~DB8	TDHT	Data hold time	10		ns
DB1~DB0 DB10~DB17	TRAT	Read access time(ID)	-	40	ns
ווטייטוטט	TRATFM	Read access time(FM)	-	340	ns
	TODH	Output disable time	20	80	ns



Reset Timing:



Reset Timing

VDDI=1.65 to 3.6V, VDD=2.4 to 3.6V, AGND=DGND=0V, Ta=25 C

Related Pins	<u>Symbol</u>	<u>Parameter</u>	<u>Min</u>	Max	<u>Unit</u>
	TRW	Reset pulse duration	10	-	us
RESET	TRT	Reset cancel	1	5 (Note 1, 5)	ms
	IRI	Reset cancer		120 (Note 1, 6, 7)	ms

Notes:

Reset Timing

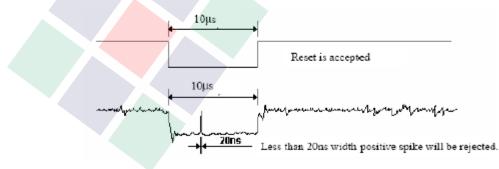
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESET Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

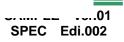
3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.

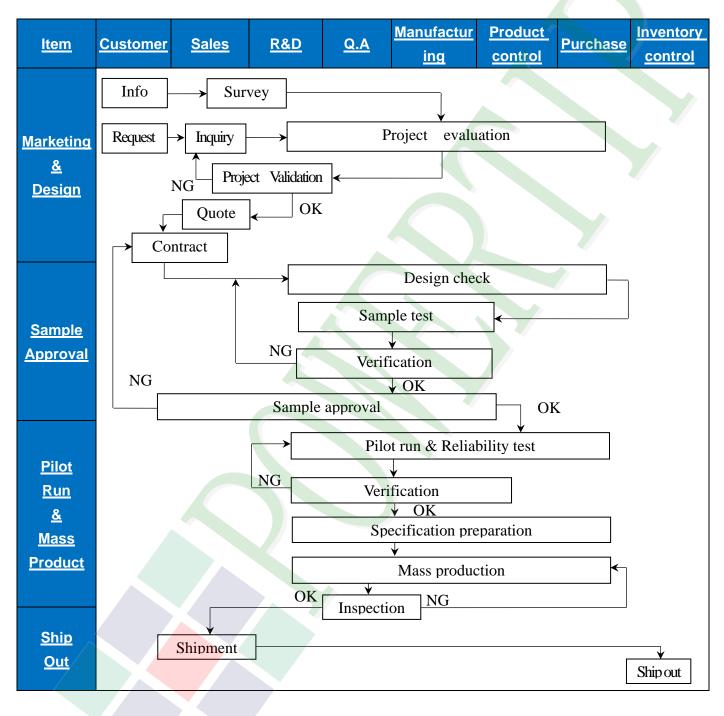
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for





3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart



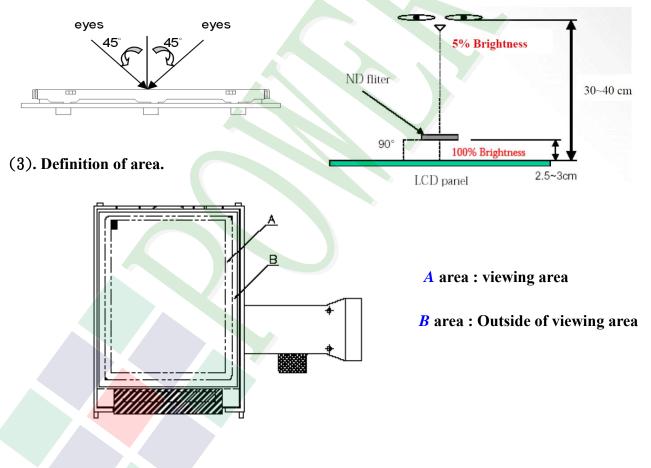


<u>ltem</u>	Customer Sales	<u>R&D</u>	<u>Q.A</u>	<u>Manufactur</u> <u>ing</u>	Product control	<u>Purchase</u>	Inventory control
	Info Claim	[Failure an	alysis		
<u>Sales</u> <u>Service</u>	Analysis report	ſ		Corrective			
		L	Track				
<u>Q.A</u> <u>Activity</u>	 ISO 9001 Maintena Equipment calibrat Standardization Maintena 	tion		2. Process im 4. Education	•		es

POWERTIP

3.2. Inspection Specification

- Scope : The document shall be applied to TFT-LCD Module for less than 3.5" (Ver.B01).
- ◆Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment : Gauge、MIL-STD、Powertip Tester、Sample
- ◆Defect Level : Major Defect AQL : 0.4 ; Minor Defect AQL : 1.5
- **OUT Going Defect Level: Sampling.**
- **♦**Standard of the product appearance test :
 - a. Manner of appearance test :
 - (1). The test best be under 20W×2 fluorescent light (about 300lux \sim 500lux)
 - and distance of view must be at 30~40 cm.
 - (2). The test direction is base on about around 45° of vertical line.



(4). Standard of inspection : (Unit : mm)



◆Specification For TFT-LCD Module Less Than 3.5″:

◆Specification For TFT-LCD Module Less Than 3.5″: (Ve				
<u>NO</u>	<u>Item</u>	<u>Criterion</u>	Level	
		1. 1The part number is inconsistent with work order of production.	Major	
01	Product condition	1. 2 Mixed product types.		
		1. 3 Assembled in inverse direction.	Major	
02	Quantity	2. 1The quantity is inconsistent with work order of production.	Major	
03	Outline dimension	3. 1 Product dimension and structure must conform to structure diagram.	Major	
		4. 1 Missing line character and icon.	Major	
		4. 2 No function or no display.	Major	
		4. 3 Display malfunction.	Major	
04	Electrical Testing	4. 4 LCD viewing angle defect.	Major	
		4. 5 Current consumption exceeds product specifications.		
		4. 6 Mura cannot be seen through 5% ND filter at 50% Gray , should be judged by the viewing angle of 90 degree.	Minor	
05	Dot defect (Bright dot \ Dark dot) On -display	Item Acceptance (O'tv) Bright Dot ≤ 2 Dot Dark Dot ≤ 3 Defect Joint Dot ≤ 2 Total ≤ 3 5.1 Inspection pattern : full white , full black , Red , Green and blue screens. 5.2 It is defined as dot defect if defect area >1/2 dot. 5.3 The distance between two dot defect ≥5 mm. 5.4 Bright dot : Dots appear bright and unchanged in visible with 5% ND filter is defined. 5.5 Tiny bright dot: bright dot area ≤1/2 dot. a. Dots appear bright and unchanged in visible with 5% ND filter is defined defect and is judged in accordance with 6.1 b. Dots invisible with 5% ND Filter is Ignored.	Minor	



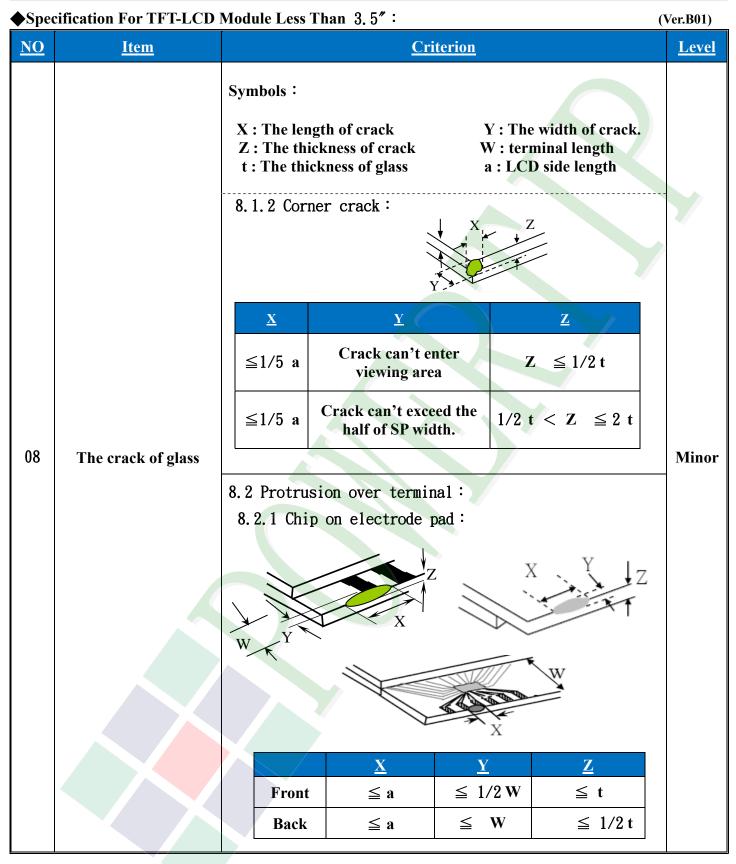
Specif	Specification For TFT-LCD Module Less Than 3.5":				
<u>NO</u>	<u>Item</u>	<u>Criterion</u>			Level
	6. 1 Round type (Non-display or display) :				
		$\frac{\underline{\text{Dimension}}}{\underline{(\text{diameter }: \Phi)}}$	<u>Acceptanc</u> <u>A area</u>	e (Q'ty) <u>B area</u>	
	Black or white dot、scratch、	$\Phi \leq 0.15$	Ignore		
	contamination	$0.15 < \Phi \leq 0.20$	2		
	Round type	$0.20 < \Phi \leq 0.30$	2	Ignore	
		$\Phi > 0.30$	0		
06	Y ↑	Total	3		Minor
	$\Phi = (x+y)/2$	6. 2 Line type(Non-display or d	display) :		
	Line type	Dimension	Accepta	nce (Q'ty)	
	$\int \frac{1}{4} W$	Length (L) Width (W)	<u>A area</u>	<u>B area</u>	
		$$ $W \leq 0.$.03 Ignore		
	L	$L \le 5.0$ 0.03 $< W \le 0.0$	05 3	Ignore	
		W >0.	.05 As round type	d	
		Total	3		
		<u>Dimension</u> (diameter : Φ)	<u>Acceptance</u> <u>A area</u>	<u>(Q'ty)</u> B area	
		$\Phi \leq 0.20$ Is	gnore		
07	Polarizer Bubble	$0.20 < \Phi \leq 0.50$	3	Ignoro	Minor
		$\Phi > 0.50$	0	Ignore	
		Total	3		



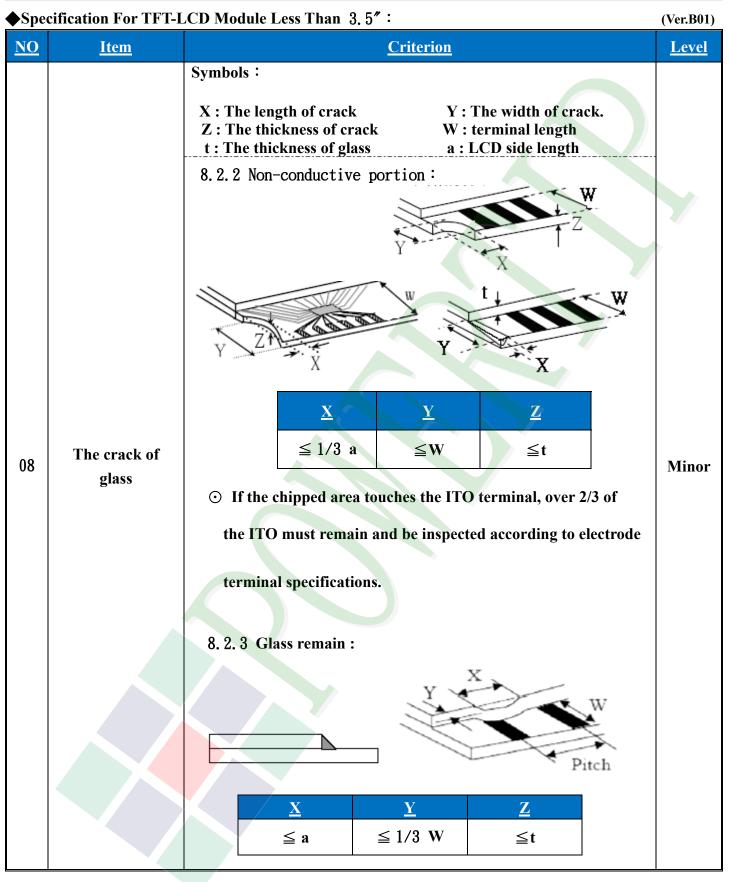
◆Specification For TFT-LCD Module Less Than 3.5″:

◆ Spec	Specification For TFT-LCD Module Less Than 3.5":				
<u>NO</u>	<u>Item</u>	<u>Criterion</u>		<u>Level</u>	
		Z : The thickness of crack	Y : The width of crack. W : terminal length a : LCD side length		
		8. 1. 1 Chip on panel surface and cra $X \rightarrow Z$ Z Z	ack between panels: X Y X		
08	The crack of glass	SP Y [OK] Seal width	ING X Y Y	Minor	
		<u>X</u> <u>Y</u>	<u>Z</u>		
		$\leq a$ Crack can't enter viewing area	$\leq 1/2 t$		
		$\leq a \qquad \begin{array}{c} Crack can't exceed the \\ half of SP width. \end{array}$	$1/2 t < Z \leq 2 t$		











◆Specification For TFT-LCD Module Less Than 3.5″:

◆Specification For TFT-LCD Module Less Than 3.5″: (Ve				
<u>NO</u>	<u>Item</u>	<u>Criterion</u>	Level	
		9. 1 Backlight can't work normally.	Major	
09	Backlight elements	9. 2 Backlight doesn't light or color is wrong.	Major	
		9. 3 Illumination source flickers when lit.	Major	
	General appearance	10. 1 Pin type 、 quantity 、 dimension must match type in structure diagram.	Major	
		10. 2 No short circuits in components on PCB or FPC.	Major	
10		10. 3 Parts on PCB or FPC must be: no wrong parts, missing parts or excess parts.	Major	
10		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor	
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor	
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≤1.5 mm.	Minor	



4. RELIABILITY TEST

4.1 Reliability Test Condition

(Ver.B01)

<u>NO.</u>	<u>TEST ITEM</u>	TEST CC	<u>ONDITION</u>			
1	High Temperature Storage Test	Keep in +80 ±5℃ 240 hrs				
2	Low Temperature Storage Test	Keep in −30 ±5°C 240 hrs				
3	High Temperature / High Humidity Storage Test	Keep in +60 °C / 90% R.H duratio (Excluding the polarizer)	Keep in +60 $^{\circ}$ C / 90% R.H duration for 240 hrs (Excluding the polarizer)			
	Tomor anothing Crusting		$\rightarrow +80^{\circ}C \rightarrow +25^{\circ}C$			
4	Temperature Cycling	(30mins) (5mins)	(30mins) (5mins)			
	Storage Test	20 0	Cycle			
		Air Discharge:	Contact Discharge:			
		Apply 2 KV with 5 times	Apply 250 V with 5 times			
	ESD Test	Discharge for each polarity +/-	discharge for each polarity +/-			
		1. Temperature ambiance : 15°C				
5		2. Humidity relative : 30%~60%				
Э		3. Energy Storage Capacitance(C	s+Cd) : 150pF±10%			
		4. Discharge Resistance(Rd) : 330	Ω±10%			
		5. Discharge, mode of operation :				
		Single discharge (time between s	uccessive discharges at least 1 sec)			
		(Tolerance if the output voltage in	dication:±5%)			
	X 791 (* 771 (1. Sine wave 10~55 Hz frequenc	y (1 min/sweep)			
6	Vibration Test (Packaged)	2. The amplitude of vibration :1.	5 mm			
	(rackageu)	3. Each direction $(X \cdot Y \cdot Z)$ dur	ration for 2 Hrs			
		Packing Weight (Kg	<u>Drop Height (cm)</u>			
		0 ~ 45.4	122			
	Drop Test	45.4 ~ 90.8	76			
7	(Packaged)	90.8 ~ 454	61			
		0ver 454	46			
		Drop Direction : ※1 corner / 3 edg	es / b sides each 1time			
©Ins _]	pection conditions after	r test:				

②Inspection conditions after test: Temperature : +20~30℃ Humidity : 50~70%

Atmospheric pressure : 86~106Kpa



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM
- 5.2.10 Caution!(LCM products with Capacitive Touch Panel)
 Strong EMI-sources such as switch-mode power supplies (SMPS) can lead to touch malfunction (e.g. ghost-touches).
 Therefore, the touch needs to be thoroughly tested inside the target application.
- 5.2.11 CAUTION: Continuously displaying same static image will result in high possibility of
 - image sticking/image burn-in effect due to TFT panel characteristic.
- 5.2.12 Double-sided tape designed to be attach with the customer's mechanical device, please follow up the rules and regulations published by the original manufacturer of double-sided tape for the attachment operation.

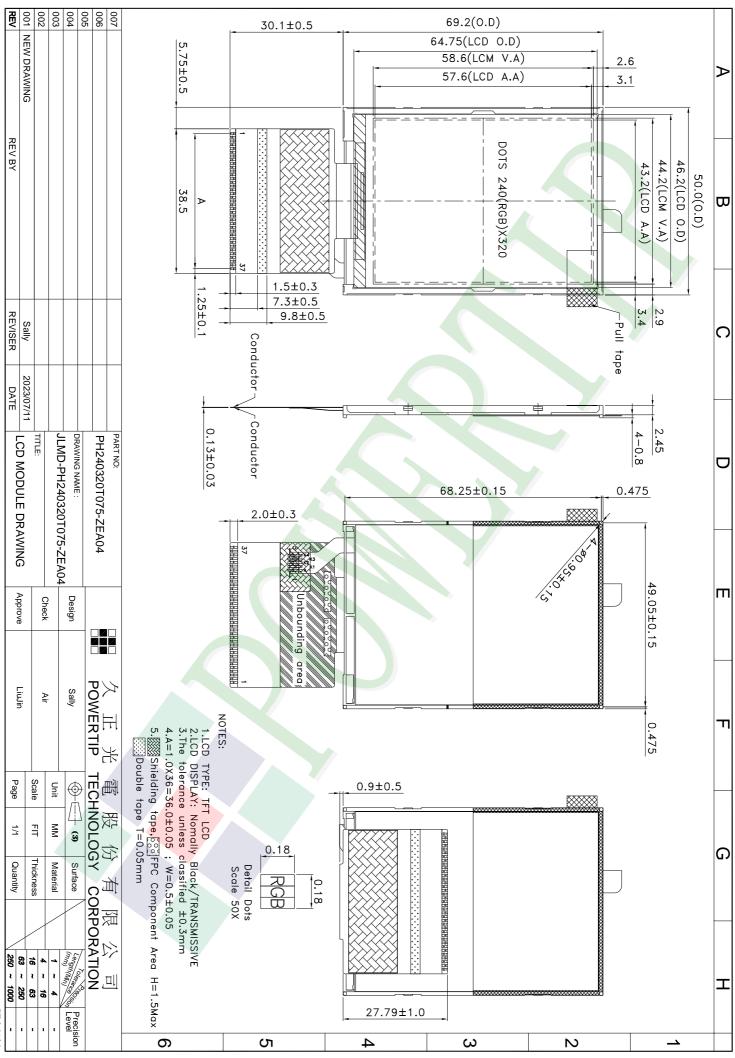
5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

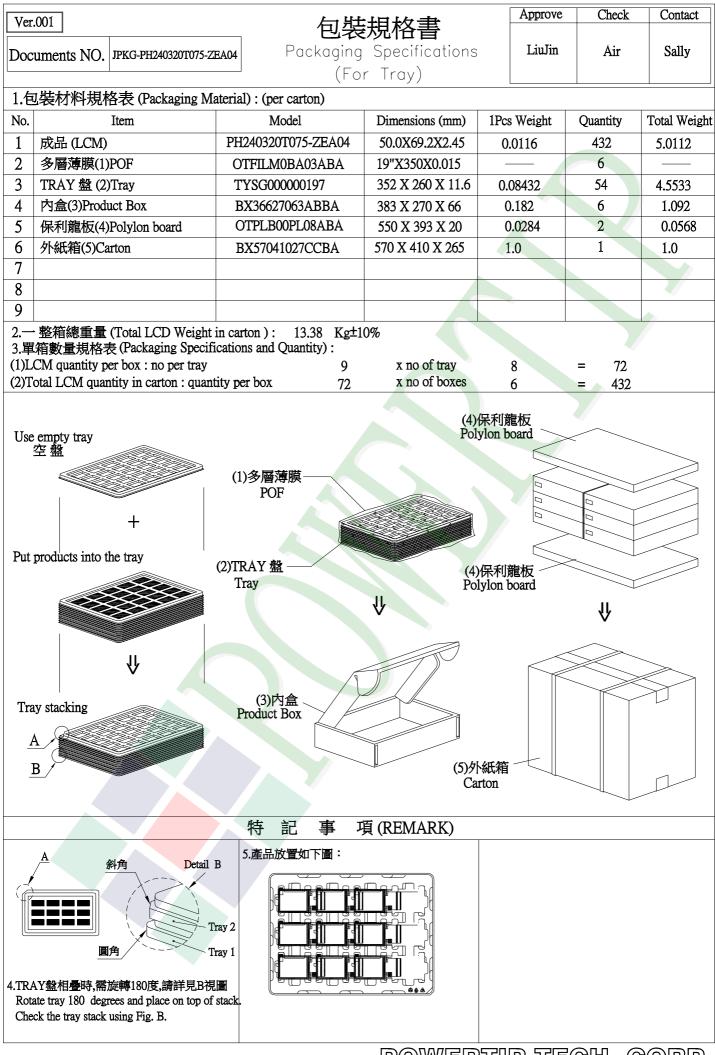
5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



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